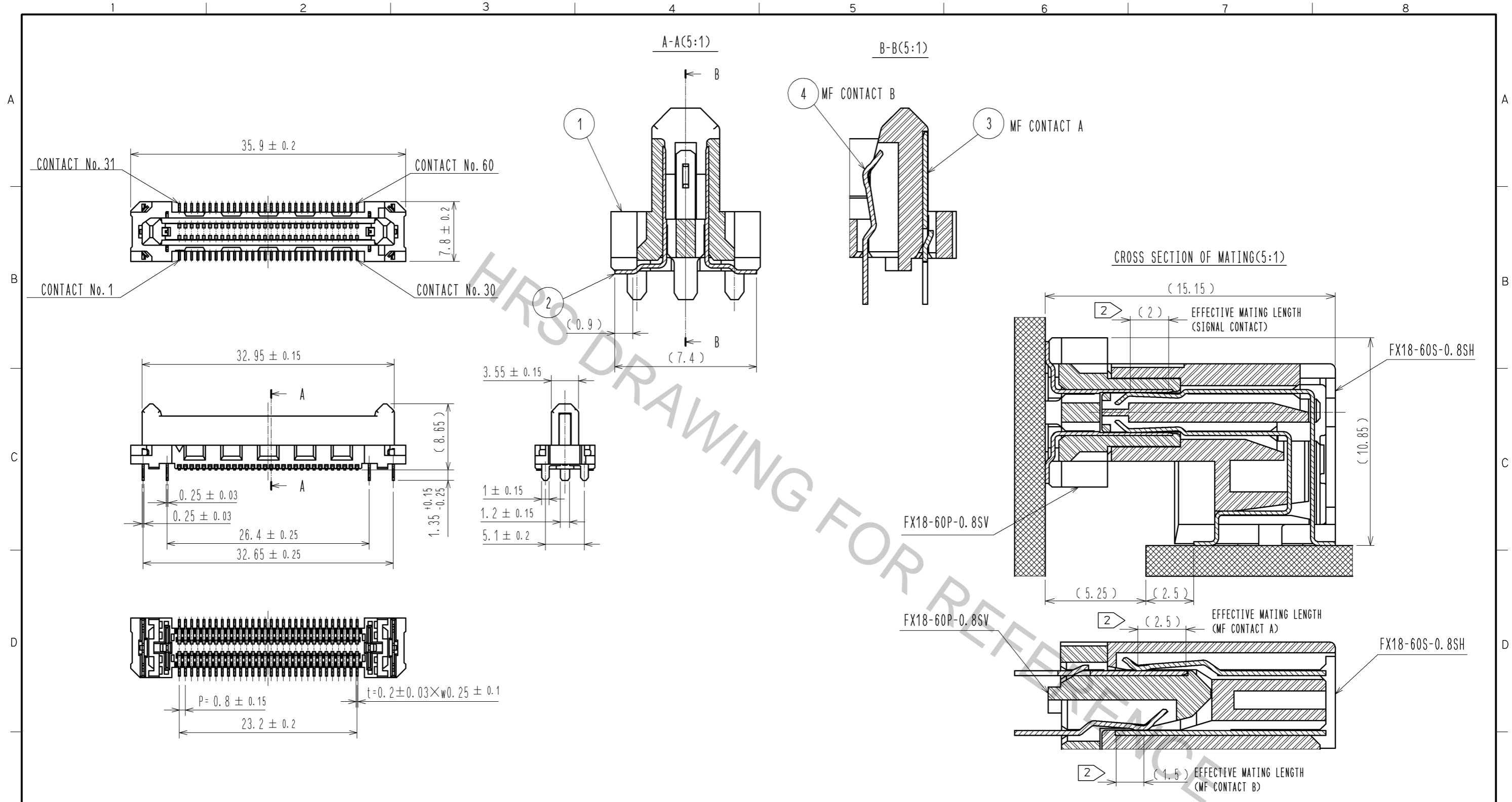


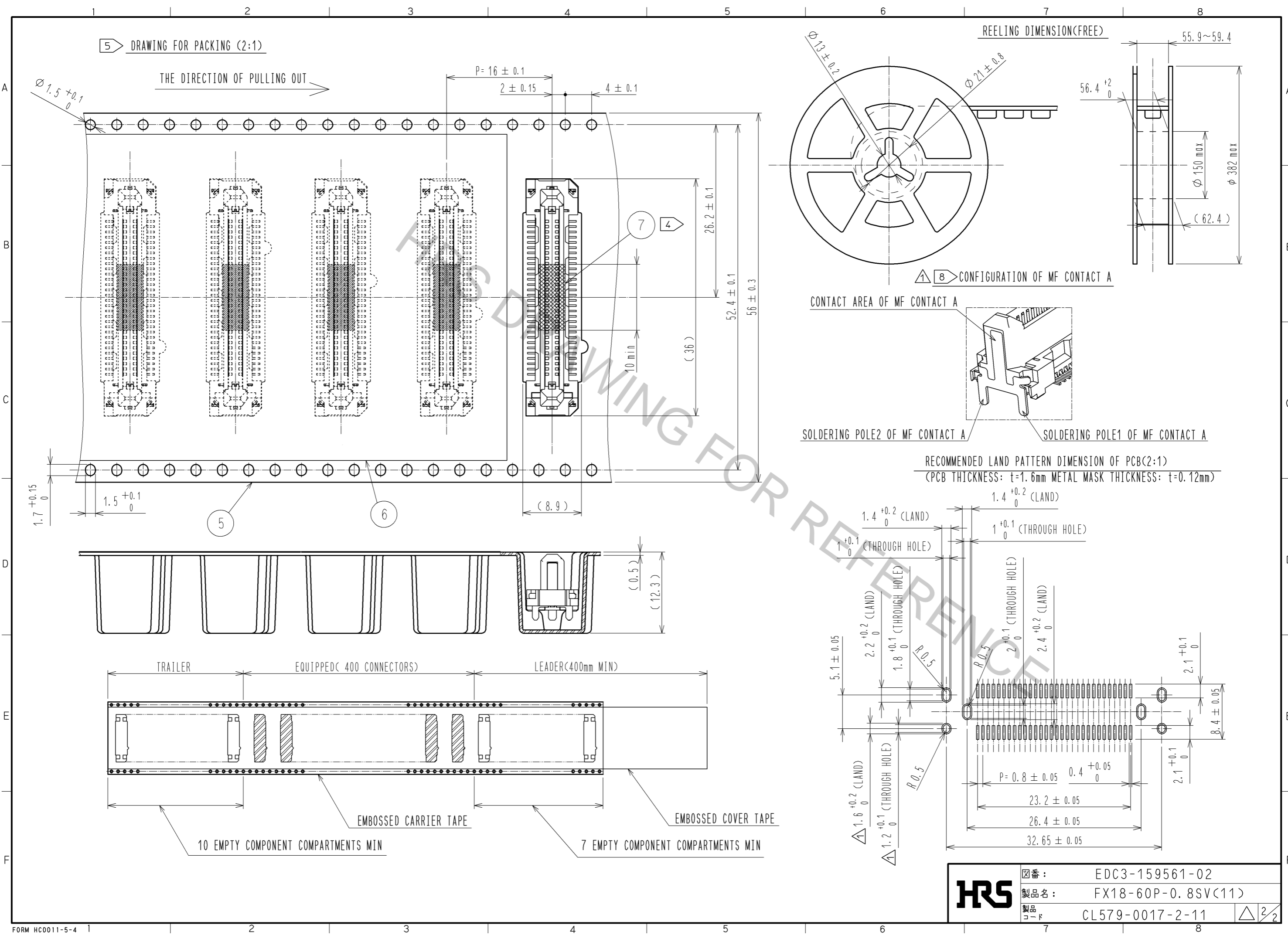
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- NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.
- ② CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A=>SIGNAL CONTACT=>MF CONTACT B)
WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.
- 3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)
- ④ IT SHOWS THE VACUUM PICKUP AREA. (SEE PAGE 2)
REMOVE THE MYLAR TAPE BEFORE MATING CONNECTORS.
- ⑤ PACKING FOR PRODUCT APPLIES EMBOSSED CARRIER TAPE PACKING. (400pcs/RL)
- 6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.
- 7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.
- ⑧ SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES.
BE SURE TO CONNECT TO THE SAME CIRCUIT.

3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm	7	POLYIMIDE	DESIGNED	TH. SANO	CHECKED	KI. HIROKAWA	DATE	11.07.21			
		LEAD AREA:TIN-PLATING 1 μm		6							POLYESTER	(EMBOSSED COVER TAPE)	
		UNDER PLATING:NICKEL 1.3 μm		5							POLYSTYRENE	(EMBOSSED CARRIER TAPE)	
2	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm	4	PHOSPHOR BRONZE	DESIGNED	TH. SANO	CHECKED	KI. HIROKAWA	DATE	11.07.21			
		LEAD AREA:GOLD 0.03 μm									4	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm
		UNDER PLATING:NICKEL 1.3 μm									4	PHOSPHOR BRONZE	LEAD AREA:TIN-PLATING 1 μm
1	POLYAMIDE	BLACK UL94V-0			DESIGNED	TH. SANO	CHECKED	KI. HIROKAWA	DATE	11.07.21			
NO.	MATERIAL	FINISH .	REMARKS	NO.	MATERIAL	FINISH .	REMARKS						

UNITS	mm	SCALE	2 : 1	COUNT	4	DESCRIPTION OF REVISIONS	DIS-F-005578	DESIGNED	TH. SANO	CHECKED	KI. HIROKAWA	DATE	11.07.21
APPROVED : HS. OKAWA		10.05.10		DRAWING NO.		EDC3-159561-02							
CHECKED : KI. HIROKAWA		10.05.10		PART NO.		FX18-60P-0.8SV(11)							
DESIGNED : TH. SANO		10.05.10		CODE NO.		CL579-0017-2-11							
DRAWN : TH. SANO		10.05.10											



HRS	図番:	EDC3-159561-02
	製品名:	FX18-60P-0.8SV(11)
	製品コード:	CL579-0017-2-11